

DESCRIPTION

- Agglomerated basic flux for submerged arc strip cladding with Soudotape NiCu7.
- Recommended for depositing a buffer layer prior to copper-nickel cladding with Soudotape CuNi30 and Record CuNi30T.

GENERAL CHARACTERISTICS

- Current DC+
- Basicity index 0.6 (according to Bonizewski; calculated in mole %)
- Grain size 0.4 – 1.4 mm (14 x 40 Mesh ASTM)
- Apparent density 0.85
- Consumption 0.5 (kg fused flux / kg strip)
- Redrying 1 to 2 hours at 350 +/- 50°C
- Applicable strip dimensions :

Strip widths (mm)	30	60
Typical deposition rates(kg/h)	8	16

TYPICAL WELD METAL ANALYSIS OF STRIP/FLUX COMBINATION (WEIGHT%)

- Base metal 0.2 % C - steel
- Strip dimensions 60 x 0.5 mm
- Cladding parameters 900 A - 26 V - 14 cm/min

Alloy	Layer	Strip Soudotape	C	Mn	Si	Ni	Fe	Cu	Ti	Thickn. (mm)
400	-	NiCu7	0.020	3.40	0.29	bal.	0.30	30.40	2	-
	1	NiCu7	0.032	2.91	0.98	bal.	18.10	25.30	0.32	4.9
	2	NiCu7	0.018	3.21	0.99	bal.	7.10	28.10	0.33	4.7

PACKING

- 25 kg (pail) :SAP Stock number : 29094.
25 kg (bag) :SAP Stock number : 29095.